

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S5	4070	(circuit board) with coat\$3 with (dielectric or insulat\$3)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 18:56
S6	2	S5 with (laser with ablation)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 18:57
S8	15	S5 with laser with (ablation or remov\$3)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 18:58
S10	6	((HANNIES) near2 (HOFMANN)). INV.	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 19:07
S20	73262	method with ((printed with circuit with board) or (circuit with board) or pcb)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/12 13:38
S21	27263	S20 and (vias or via or trench or recess)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/12 13:39
S22	15426	S21 and (dielectric or insulat\$3)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 13:40
S23	620	S22 and (laser with ablation)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 13:40

S29	1072	laser with ((direct-write) or (direct write))	US-PGRUB; USPAT; USOCR	ADJ	ON	2009/05/12 17:30
S30	4	S29 with ((printed with circuit with board) or (circuit with board) or pcb)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/12 17:31
S34	4073	(circuit board) with coat\$3 with (dielectric or insulat\$3)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:45
S35	1	S34 with (puls\$3 with laser)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:45
S36	215	S34 and laser with (ablat\$3 or remov\$3)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:47
S37	37	S36 and (puls\$3 with laser)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:47
S38	91	laser with ((direct-write) or (direct write)) with (puls\$3 with laser)	US-PGRUB; USPAT; USOCR	ADJ	ON	2009/05/12 18:50
S47	73262	method with ((printed with circuit with board) or (circuit with board) or pcb)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:10
S49	50	S47 and (horizontal with technique)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:11
S50	73262	method with ((printed with circuit with board) or (circuit with board) or pcb)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:30

S53	371	(205/80).CQLS.	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:32
S54	0	(219/121.690).CQLS.	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:33
S57	3654	(428/209).CQLS.	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:35
S62	3705	(428/209).CQLS.	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/11/02 09:44
S63	252	S62 and laser with (ablat\$3 or remov\$3)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/02 09:44
S69	199763	sputtering	US-PGRUB; USPAT; USOCR	ADJ	ON	2009/11/02 15:35
S70	250429	"428"/\$.ccls.	US-PGRUB; USPAT; USOCR	ADJ	ON	2009/11/02 15:35
S71	12638	S70 AND S69	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/02 15:36
S72	464	S71 and (pcb or printed circuit board)	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/02 15:37
S79	8352	(29/ 830,831,832,852).CQLS.	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/01/21 16:52
S80	47	S79 and (PCB or (print\$3 circuit board)) and traces and dielectric and (laser ablation)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 16:53

S83	91	S79 and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 17:51
S84	58	S83 not S80	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 17:51
S86	31	(high density interconnection) and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 18:29
S87	49	(high density interconnection) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 18:48

**EAST Search History (Interference)**

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